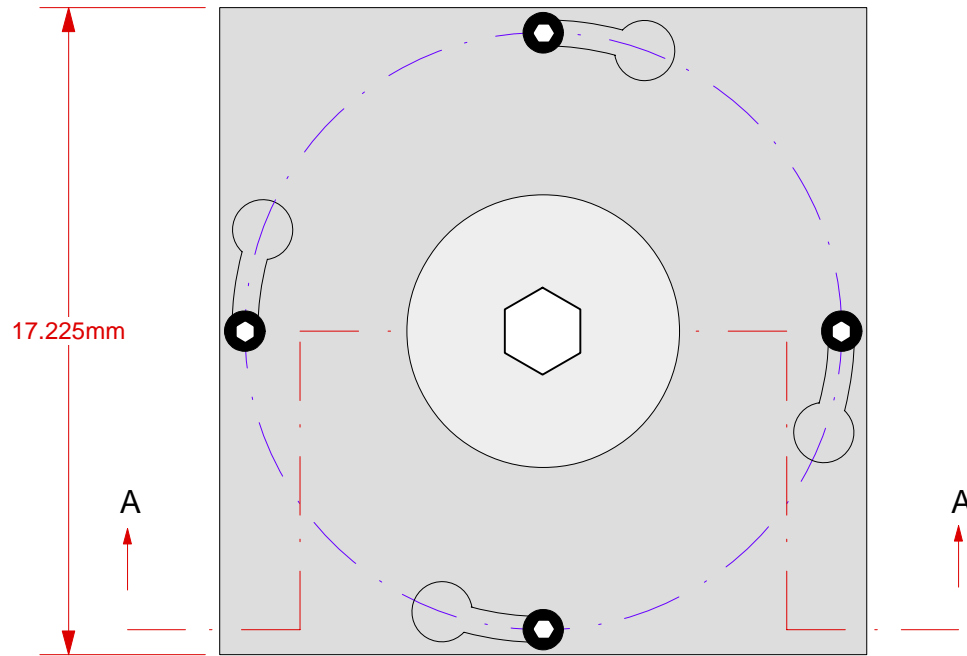
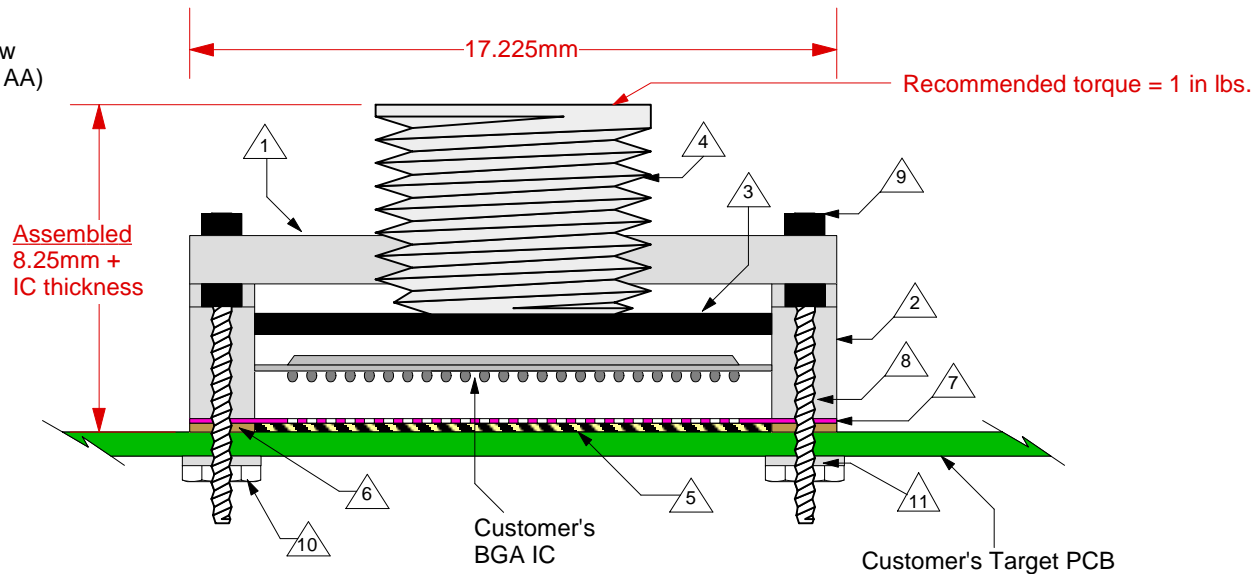


GHz BGA Socket - Direct mount, solderless

Top View



Side View
(Section AA)



Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid

- △ 1 Socket Lid: Black anodized 6061 Aluminum. Thickness = 2.5mm.
- △ 2 Socket base: Black anodized 6061 Aluminum. Thickness = 5mm.
- △ 3 Compression Plate: Black anodized 6061 Aluminum. Thickness = 2.5mm.
- △ 4 Compression screw: Black anodized 6061 Aluminum. Thickness = 5mm, Hex socket = 5mm.
- △ 5 Elastomer: 30 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- △ 6 Elastomer Guide: Non-clad FR4. Thickness = 0.75mm.
- △ 7 Ball Guide: Kapton polyimide.
- △ 8 Socket base screw: Socket head cap, 18-8 Stainless steel, 0-80 fine thread , 9.525mm long.
- △ 9 Socket lid screw: Socket head cap, 18-8 Stainless steel, 0-80 fine thread , 4.76mm long.
- △ 10 Socket base nut: 18-8 Stainless steel, 0-80 fine thread.
- △ 11 Nylon washer: 1.73mm ID; 4.78mm OD 0.64mm thickness.

SG-BGA-6001 Drawing

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PO BOX 21151 ST. PAUL, MN 55121
Tele: (651) 452-8100
www.ironwoodelectronics.com

Status: Released

Scale: -

Rev: A

Drawing: Ila Pal

Date: 8/14/01

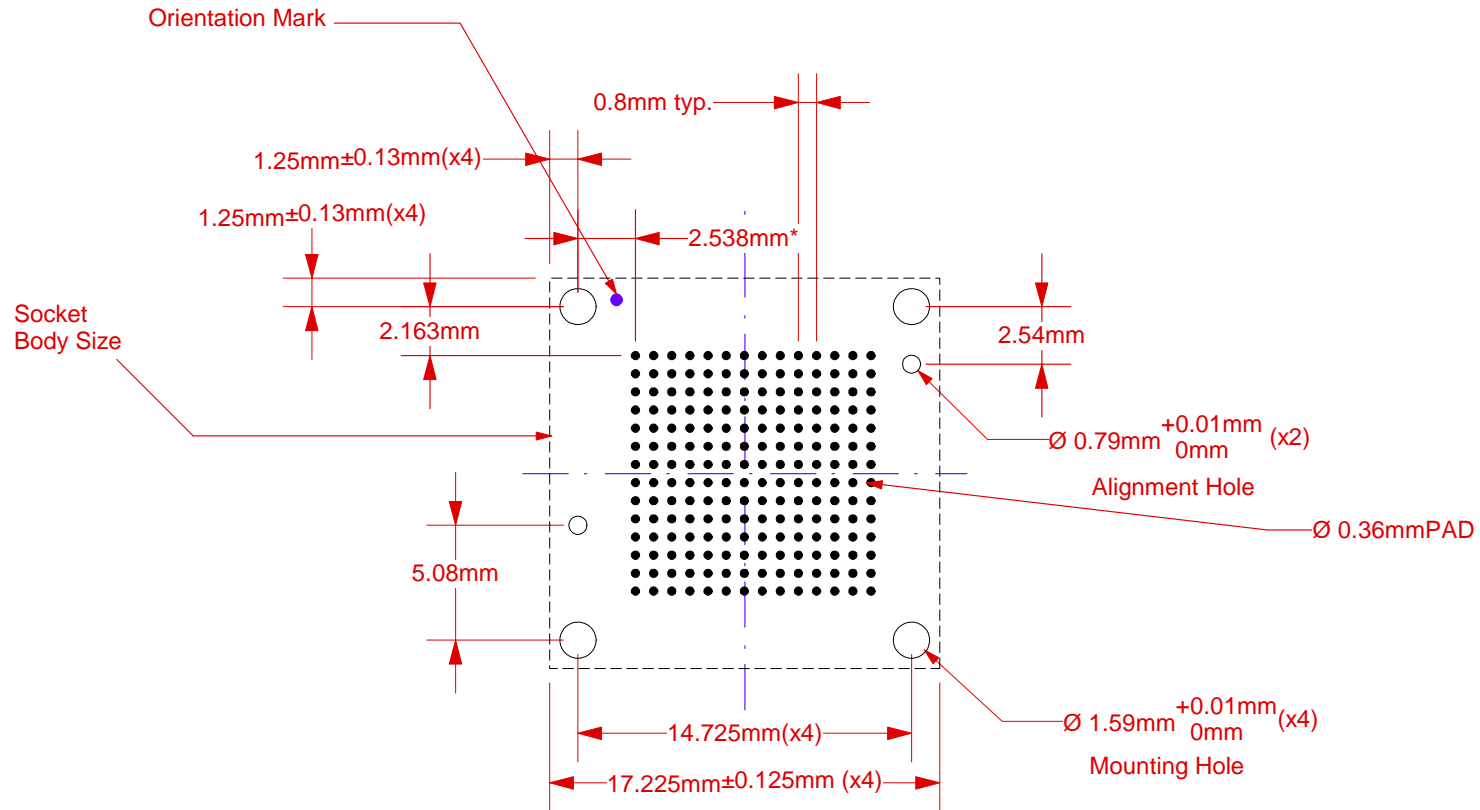
File: SG-BGA-6001 Dwg.mcd

Modified:

All tolerances: ± 0.125 mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**




Target PCB Recommendations

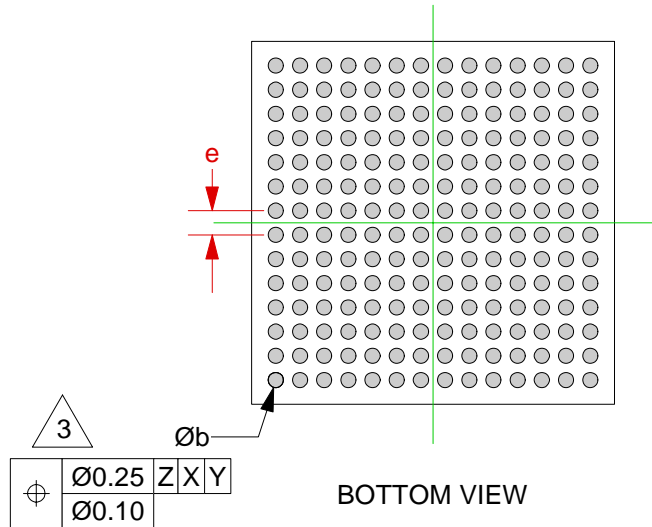
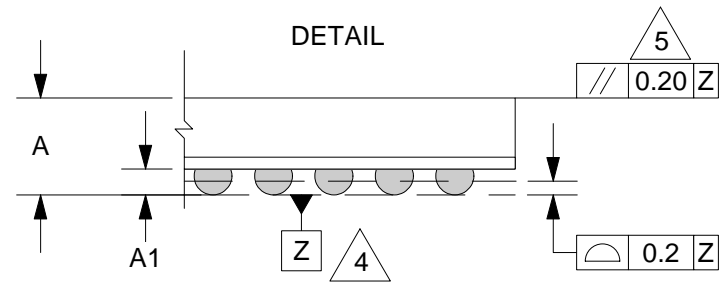
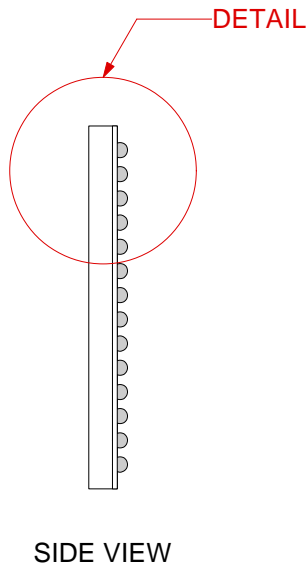
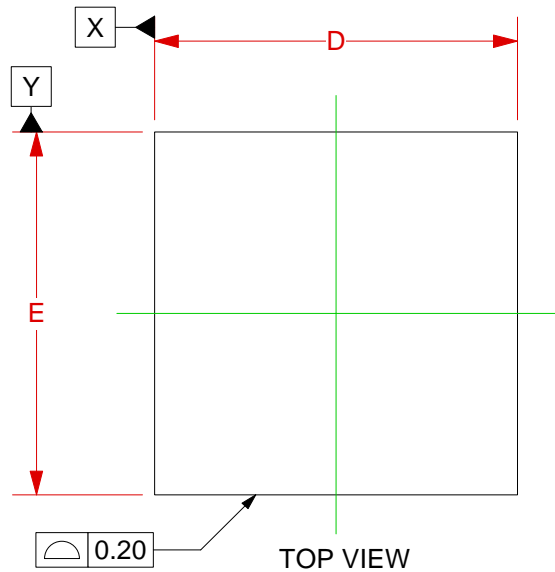
Total thickness: 1.6mm or high
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: $\pm 0.025mm$ [$\pm 0.001"$] unless stated otherwise.

	SG-BGA-6001 Drawing	Status: Released	Scale: 3:1	Rev: A
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		File: SG-BGA-6001 Dwg.mcd	Modified:	

Compatible BGA Spec



1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.


3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.

4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.

5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.5
A1	0.15	0.4
b		0.50
D	12.00 BSC	
E	12.00 BSC	
e	0.80 BSC	

Array 14x14

	SG-BGA-6001 Drawing	Status: Released	Scale: -	Rev: A
	© 2001 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing: Ila Pal		Date: 8/14/01
		File: SG-BGA-6001 Dwg.mcd	Modified:	